MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model : MI0570QT-3

This module uses ROHS material

For Customer's Acceptance:

Customer	
Approved	
Comment	

This specification may change without prior notice in order to improve performance or quality. Please contact Multi-Inno for updated specification and product status before design for this product or release of this order.	Revision	1.0
	Engineering	
	Date	2013-07-02
	Our Reference	

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2013-07-02	First Release	

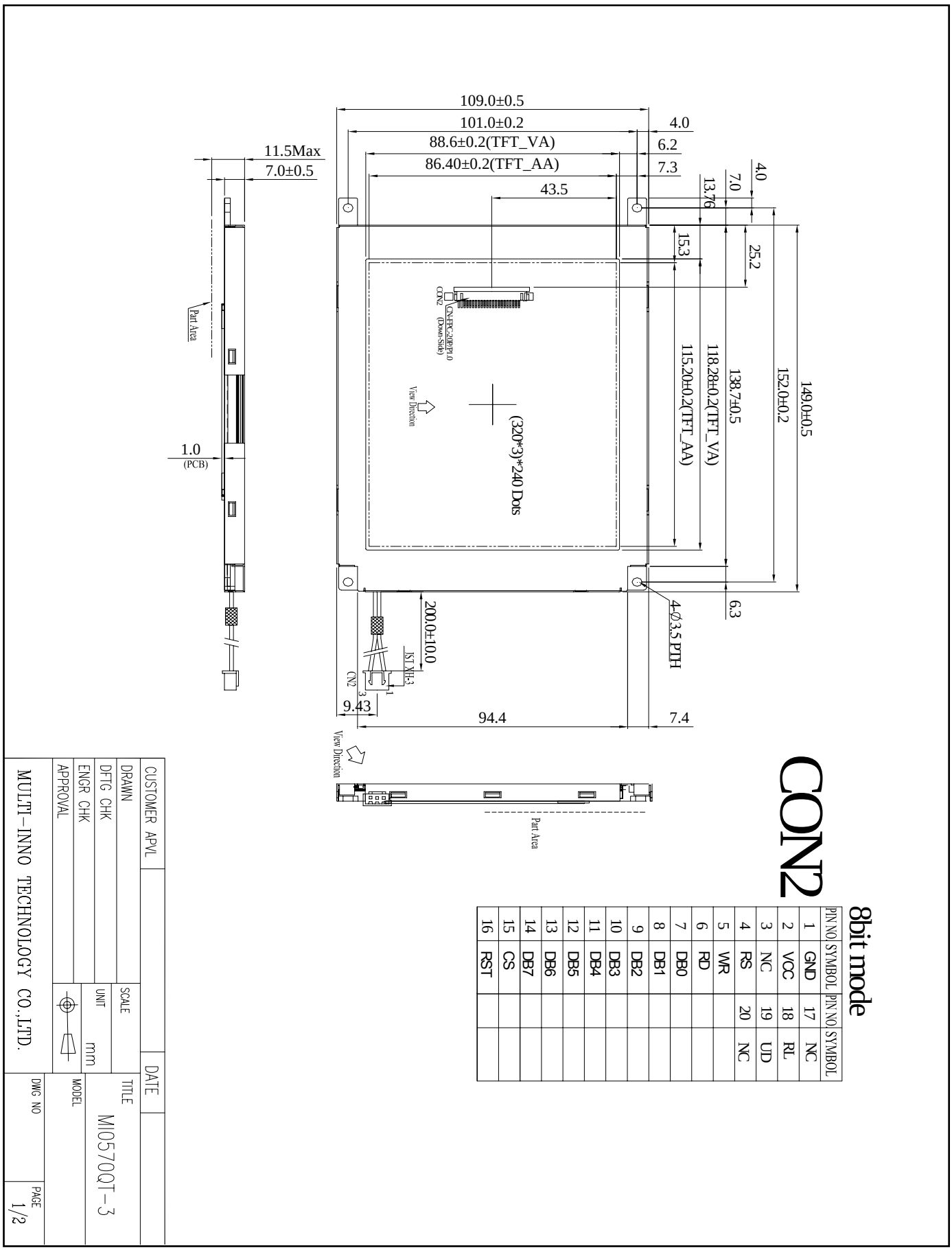
CONTENTS

■ GENERAL INFORMATION

Item	Contents	Unit
LCD type	TFT/Transmissive/Normally white	/
Size	5.7	Inch
Viewing direction	12:00	O' Clock
Gray scale inversion direction	6:00	O' Clock
LCM (W × H × D)	149.0×109.0×11.5	mm^3
Active area (W×H)	115.2×86.4	mm^2
Dot pitch (W×H)	0.12×0.36	mm^2
Number of dots	320 (RGB) × 240	/
Driver IC	SSD1963	/
Backlight type	21 LEDs	/
Interface type	8-bit MPU	/
Color depth	262K	/
Input voltage	3.3	V
With/Without TSP	Without TSP	/
Weight	TBD	g

Note 1:Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.
Note 2 : RoHS compliant
Note 3: LCM weight tolerance: ± 5% .

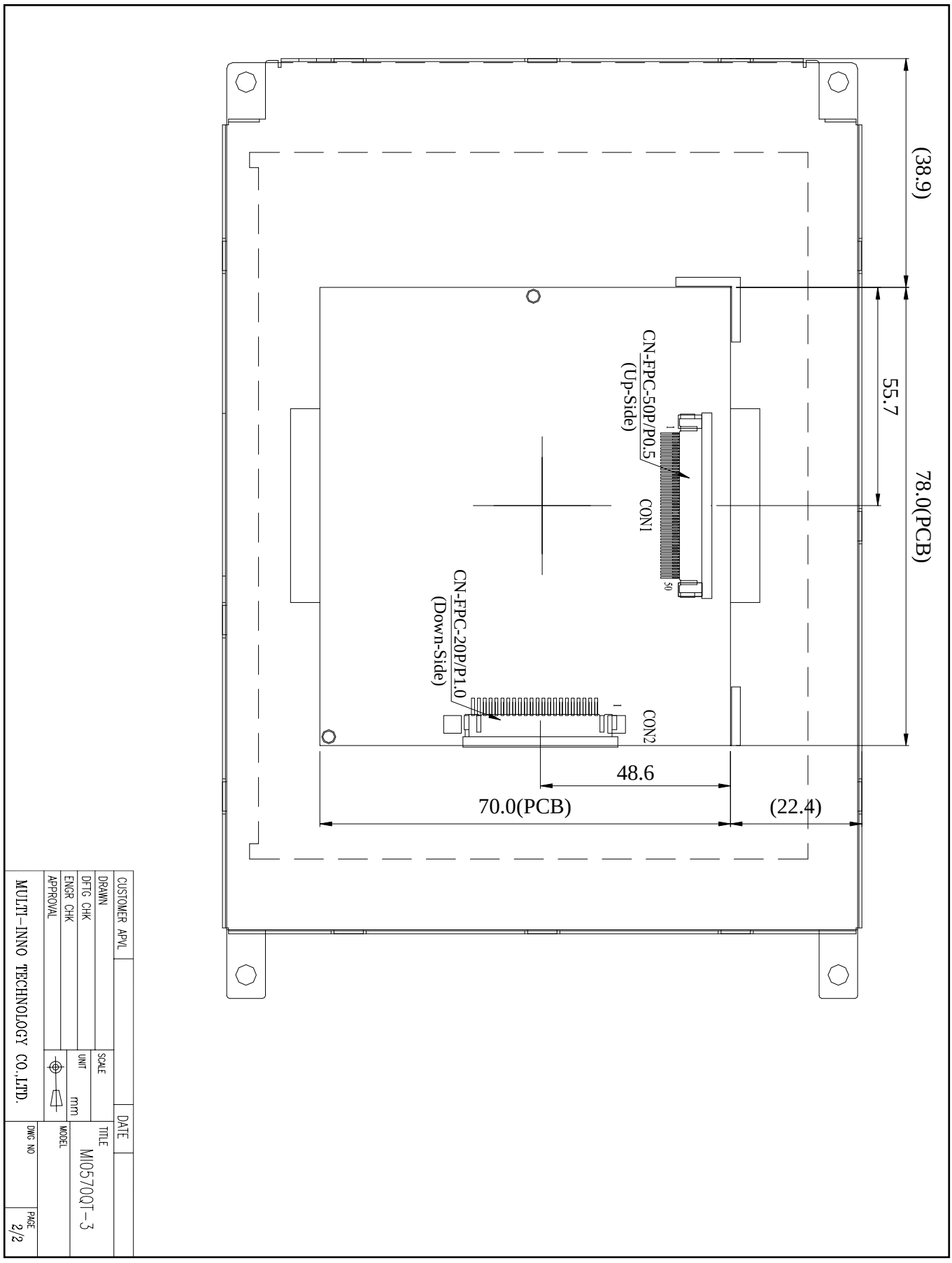
■ EXTERNAL DIMENSIONS



CON2

8bit mode

PIN NO	SYMBOL	PIN NO	SYMBOL
1	GND	17	NC
2	VCC	18	RL
3	NC	19	UD
4	RS	20	NC
5	WR		
6	RD		
7	DB0		
8	DB1		
9	DB2		
10	DB3		
11	DB4		
12	DB5		
13	DB6		
14	DB7		
15	CS		
16	RST		


(38.9)
55.7
78.0(PCB)
CN-FPC-50P/P0.5
(Up-Side)
CON1
1
50
CN-FPC-20P/P1.0
(Down-Side)
CON2
1
48.6
70.0(PCB)
(22.4)
CUSTOMER APVL
DRAWN
DFTG CHK
ENGR CHK
APPROVAL
DATE
SCALE
UNIT
mm
MULTI-INNO TECHNOLOGY CO.,LTD.
TITLE
MI0570QT-3
MODEL
DWG NO
PAGE
2/2

■ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Power supply for logic	VDD	-0.3	3.5	V
Power supply for analog	AVDD	-0.3	5.5	V
Input voltage	VI	-0.3	VDD	V
Operating temperature	TOP	-20	70	°C
Storage temperature	TST	-30	80	°C
Humidity	RH	-	90%(Max60°C)	RH

■ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage for logic	VDD	3.0	3.3	3.5	V
Supply current	IVDD	-	121	-	mA
Input voltage ' H ' level	VIH	0.7VDD	-	VDD	V
Input voltage ' L ' level	VIL	0	-	0.3VDD	V

■DC CHARACTERISTICS

Conditions:

Voltage referenced to VSS

VDDD, VDDPLL = 1.2V

VDDIO, VDDLCD = 3.3V

TA = 25℃

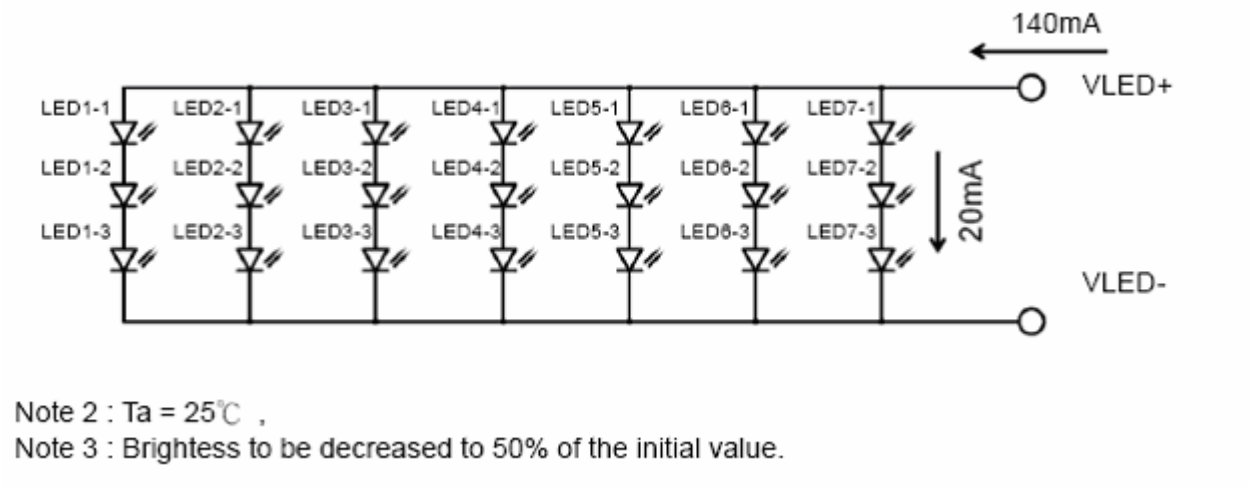
DC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
PSTY	Quiescent Power			300	500	uW
IIZ	Input leakage current		-1		1	uA
IOZ	Output leakage current		-1		1	uA
VOH	Output high voltage		0.7VDDIO			V
VOL	Output low voltage				0.3VDDIO	V
VIH	Input high voltage		0.7VDDIO		VDDIO+0.2	V
VIL	Input low voltage				0.3VDDIO	V

■ BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Typ.	Max.	Unit	Condition
LED current	I_{LED}	-	140	-	mA	Note 1
LED voltage	V_{LED}	9.0	-	10.5	V	Note 5
LED life time	-	-	50,000	-	Hrs	Note 2,3,4

Note 1: There are 7 Groups LED shown as below, =9.9 V(Min)



Note 2 : Ta = 25℃ ,
Note 3 : Brightess to be decreased to 50% of the initial value.

Note 4: 50K hours is only an estimate for reference.

Note 5: The LED of B/L is drive by current only；driving voltage is only for reference .

■ELECTRO-OPTICAL CHARACTERISTICS

Item		Symbol	Condition	Min	Typ	Max	Unit	Remark	Note
Response time		Tr+Tf	θ=0° ∅=0° Ta=25℃	-	50	-	ms	FIG 1.	4
Contrast ratio		Cr		-	250	-	---	FIG 2.	1
Luminance uniformity		δ WHITE		-	TBD	-	%	FIG 2.	3
Surface Luminance		Lv		300	-	-	cd/m^2	FIG 2.	2
Viewing angle range		CR=10	∅ = 90°	-	40	-	deg	FIG 3.	6
			∅ = 270°	-	60	-	deg	FIG 3.	
			∅ = 0°	-	60	-	deg	FIG 3.	
			∅ = 180°	-	65	-	deg	FIG 3.	
Viewing angle range		CR=5	∅ = 90°	-	60	-	deg	FIG 3.	6
			∅ = 270°	-	70	-	deg	FIG 3.	
			∅ = 0°	-	70	-	deg	FIG 3.	
			∅ = 180°	-	70	-	deg	FIG 3.	
CIE (x, y) chromaticity	Red	x	θ=0° ∅=0° Ta=25℃	0.50	0.55	0.60		FIG 2.	5
		y		0.26	0.31	0.36			
	Green	x		0.25	0.30	0.35			
		y		0.53	0.58	0.63			
	Blue	x		0.10	0.15	0.20			
		y		0.05	0.10	0.15			
	White	x		0.26	0.31	0.36			
		y		0.29	0.34	0.39			
NTSC	-	-	-	-	50	-	%	-	-

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.

$$\text{Contrast Ratio} = \frac{\text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Average Surface Luminance with all black pixels (P1, P2, P 3,P4, P5)}}$$

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)

Note 3. The uniformity in surface luminance ， δ WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta\ \text{WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)}}{\text{Maximum Surface Luminance with all white pixels (P1, P2, P 3, P4, P5)}}$$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series.

Note 5. CIE (x, y) chromaticity，The x, y value is determined by measuring luminance at each test position 1 through 5,and then make average value.

Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments For contrast ratio, Surface Luminance, Luminance uniformity, CIE The test data is base on TOPCON's BM-5 photo detector.

FIG. 1 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".

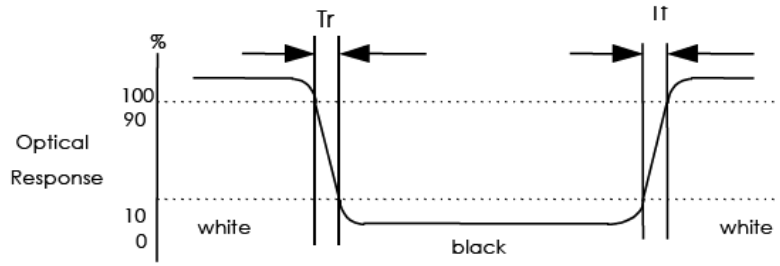
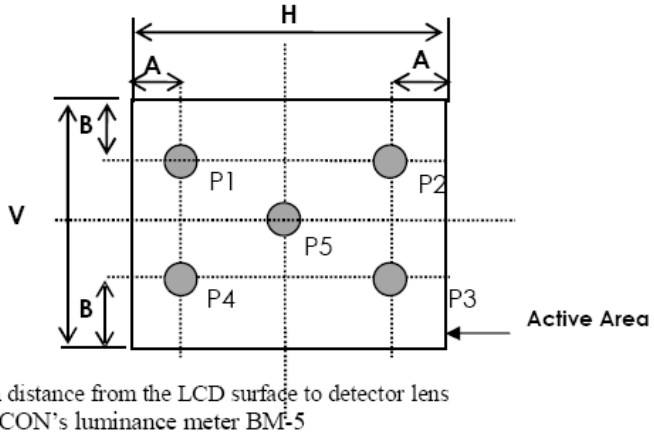
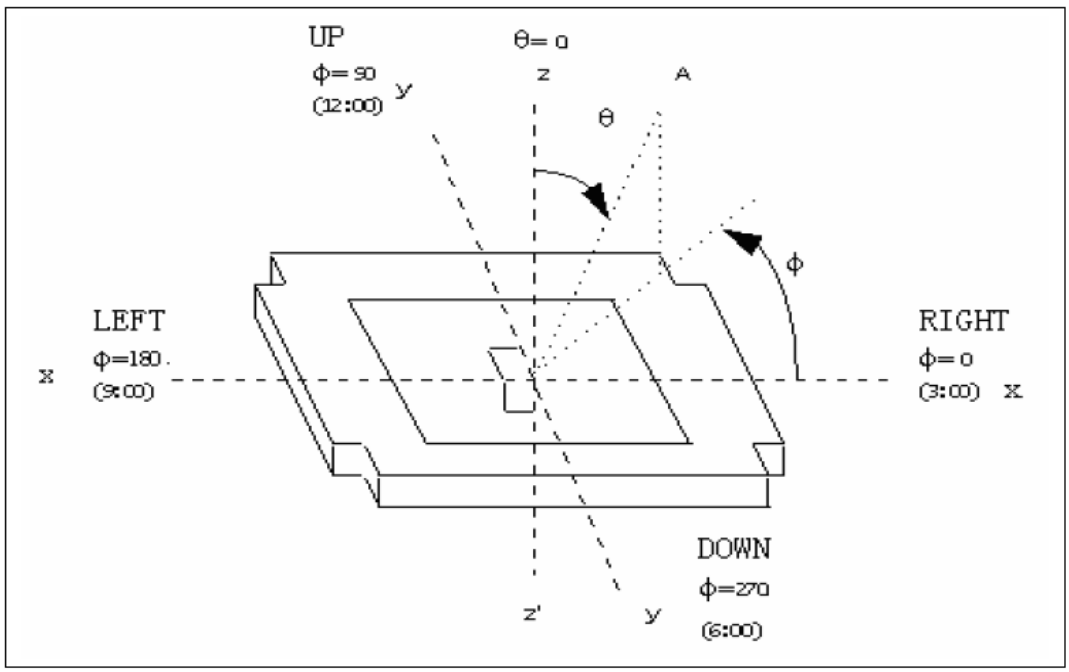


FIG. 2 Measuring method for Contrast ratio, surface luminance, Luminance uniformity , CIE (x, y) chromaticity



A : 5 mm
B : 5 mm
H,V : Active Area
Light spot size ∅=7mm, 500mm distance from the LCD surface to detector lens
measurement instrument is TOPCON's luminance meter BM-5

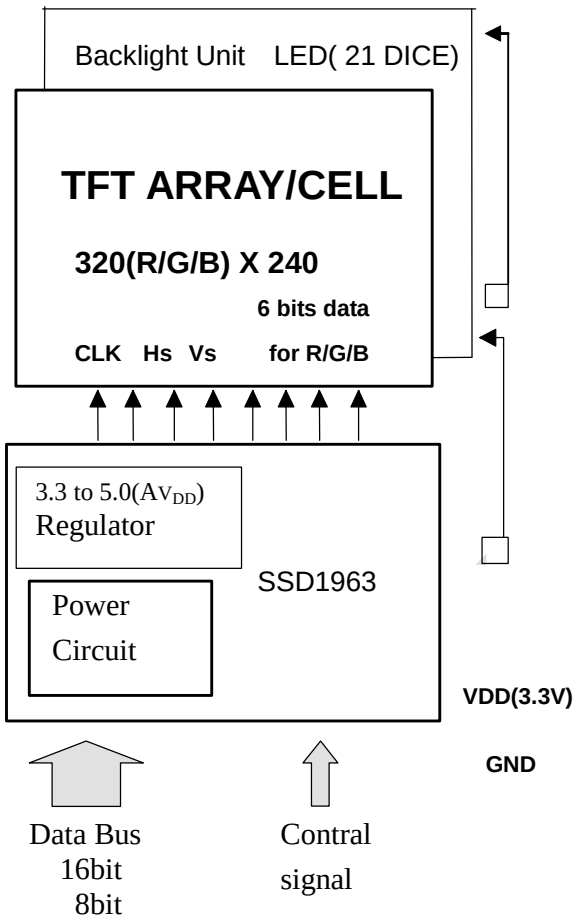
FIG. 3 The definition of viewing angle



■ INTERFACE DESCRIPTION

P/N	Symbol	8 B IT Function
1	GND	Ground
2	VCC	Power supply for Logic
3	NC	No connection
4	RS	Command/Data select(L: Command, H: Data)
5	WR	8080 family MPU interface : Write signal
6	RD	8080 family MPU interface: Read signal
7	DB0	Data bus
8	DB1	
9	DB2	
10	DB3	
11	DB4	
12	DB5	
13	DB6	
14	DB7	
15	CS	Chip select
16	RES	RESET
17	NC	No connection
18	RL	Scan direction
19	UD	Scan direction
20	NC	No connection

■ BLOCK DIAGRAM



■ APPLICATION NOTES

1. AC Characteristics

Conditions:

Voltage referenced to VSS

VDDD, VDDPLL = 1.2V

VDDIO, VDDLCD = 3.3V

TA = 25℃

CL = 50pF (Bus/CPU Interface)

CL = 0pF (LCD Panel Interface)

1.1 Clock Timing

Table 10-1:Clock Input Requirements for CLK (PLL-bypass)

Symbol	Parameter	Min	Max	Units
FCLK	Input Clock Frequency (CLK)		110	MHz
TCLK	Input Clock period (CLK)	1/fCLK		ns

Table 1-2: Clock Input Requirements for CLK

Symbol	Parameter	Min	Max	Units
FCLK	Input Clock Frequency (CLK)	2.5	50	MHz
TCLK	Input Clock period (CLK)	1/fCLK		ns

Table 1-3: Clock Input Requirements for crystal oscillator XTAL

Symbol	Parameter	Min	Max	Units
FXTAL	Input Clock Frequency	2.5	10	MHz
TXTAL	Input Clock period	1/fXTAL		ns

1.2 MCU Interface Timing

1.2.1 Parallel 6800-series Interface Timing

Table 1-4: Parallel 6800-series Interface Timing Characteristics (Use CS as clock)

Symbol	Parameter		Min	Typ	Max	Unit
fMCLK	System Clock Frequency*		1	-	110	MHz
tMCLK	System Clock Period*		1/ fMCLK	-	-	ns
tPWCSH	Control Pulse High Width	Write Read	13 30	1.5* tMCLK 3.5* tMCLK	-	ns
tPWCSL	Control Pulse Low Width	Write (next write cycle) Write (next read cycle) Read	13 80 80	1.5* tMCLK 9* tMCLK 9* tMCLK	-	ns
tAS	Address Setup Time		2	-	-	ns
tAH	Address Hold Time		2	-	-	ns
tDSW	Data Setup Time		4	-	-	ns
tDHW	Data Hold Time		1	-	-	ns
tPLW	Write Low Time		14	-	-	ns
tPHW	Write High Time		14	-	-	ns
tPLWR	Read Low Time		38	-	-	ns
tACC	Data Access Time		32	-	-	ns
tDHR	Output Hold time		1	-	-	ns
tR	Rise Time		-	-	0.5	ns
tF	Fall Time		-	-	0.5	ns

* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)

Figure 1-1: Parallel 6800-series Interface Timing Diagram (Use CS as Clock)

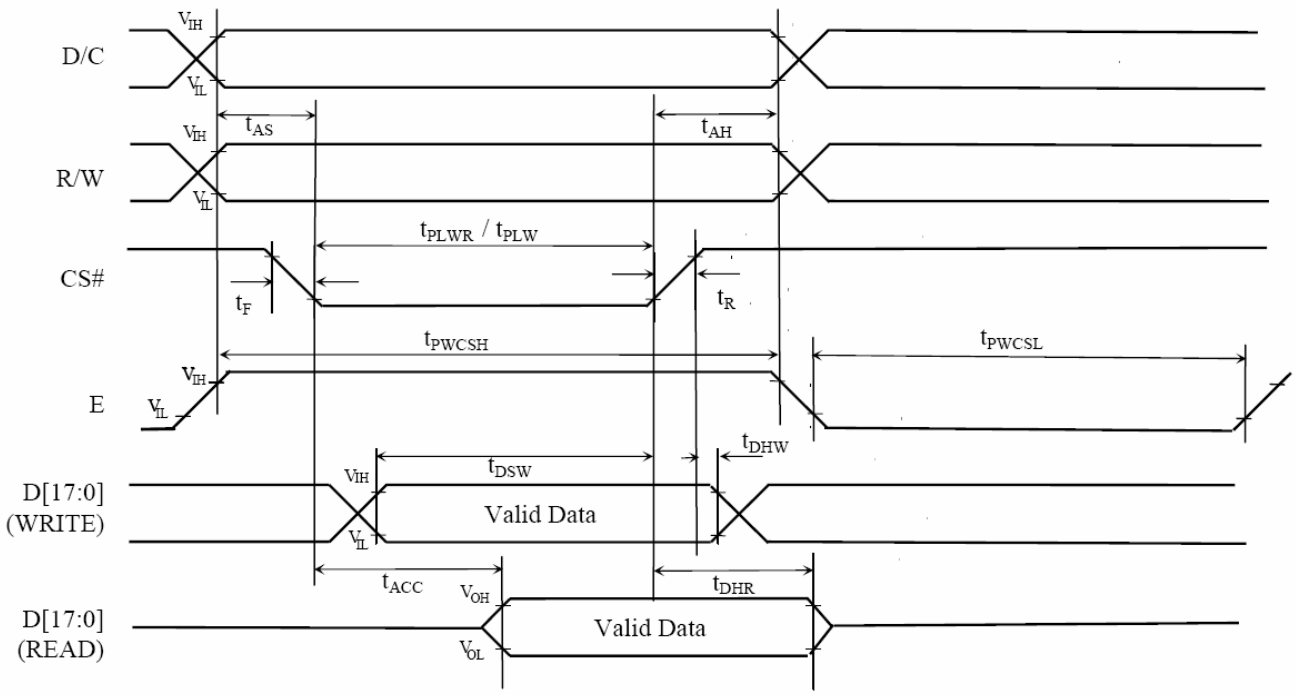
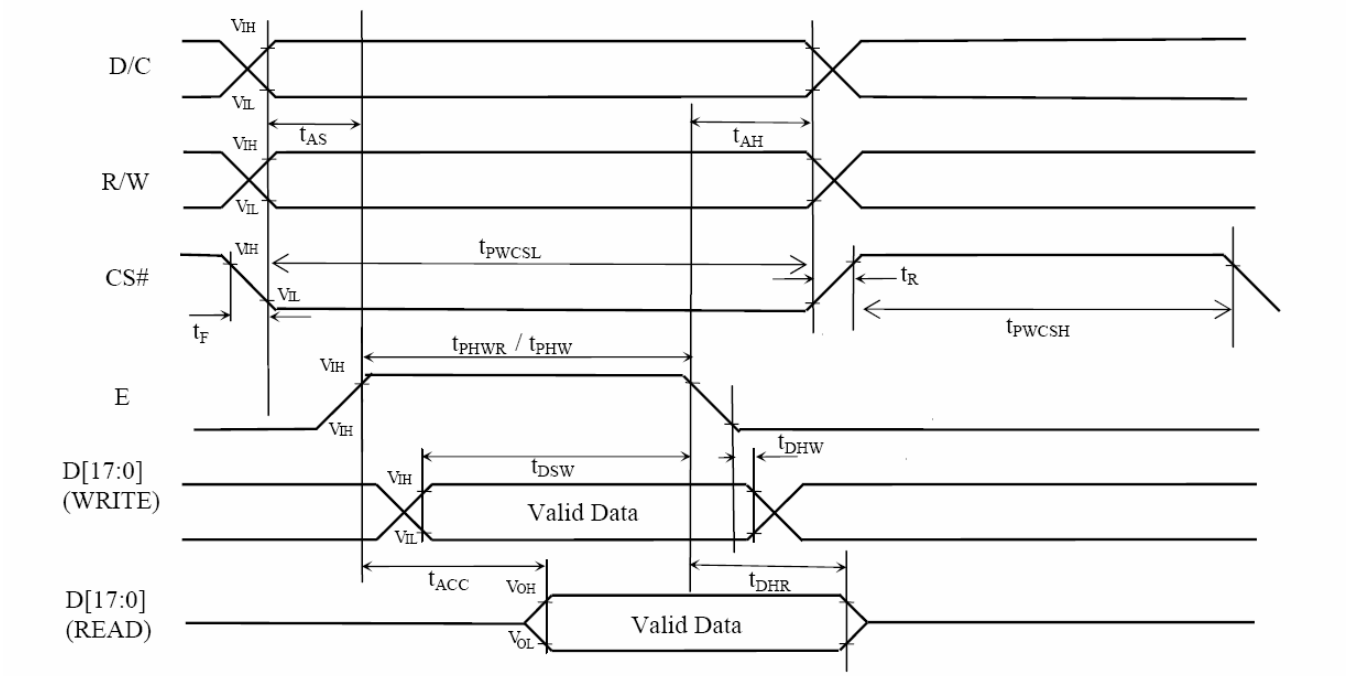


Table 1-5: Parallel 6800-series Interface Timing Characteristics (Use E as clock)

Symbol	Parameter		Min	Typ	Max	Unit
fMCLK	System Clock Frequency*		1	-	110	MHz
tMCLK	System Clock Period*		1/ fMCLK	-	-	ns
tPWCSH	Control Pulse High Width	Write (next write cycle) Write (next read cycle) Read	13 80 80	1.5* tMCLK 9* tMCLK 9* tMCLK	-	ns
tPWCSL	Control Pulse Low Width	Write Read	13 30	1.5* tMCLK 3.5* tMCLK	-	ns
tAS	Address Setup Time		2	-	-	ns
tAH	Address Hold Time		2	-	-	ns
tDSW	Data Setup Time		4	-	-	ns
tDHW	Data Hold Time		1	-	-	ns
tPLW	Write Low Time		14	-	-	ns
tPHW	Write High Time		14	-	-	ns
tPLWR	Read Low Time		38	-	-	ns
tACC	Data Access Time		32	-	-	ns
tDHR	Output Hold time		1	-	-	ns
tR	Rise Time		-	-	0.5	ns
tF	Fall Time		-	-	0.5	ns

* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)

Figure1-2: Parallel 6800-series Interface Timing Diagram (Use E as Clock)



1.2.2 Parallel 8080-series Interface Timing

Table 1-6: Parallel 8080-series Interface

Symbol	Parameter		Min	Typ	Max	Unit
fMCLK	System Clock Frequency*		1	-	110	MHz
tMCLK	System Clock Period*		1/ fMCLK	-	-	ns
tPWCSL	Control Pulse High Width	Write Read	13 30	1.5* tMCLK 3.5* tMCLK	-	ns
tPWCSH	Control Pulse Low Width	Write (next write cycle) Write (next read cycle) Read	13 80 80	1.5* tMCLK 9* tMCLK 9* tMCLK	-	ns
tAS	Address Setup Time		1	-	-	ns
tAH	Address Hold Time		2	-	-	ns
tDSW	Write Data Setup Time		4	-	-	ns
tDHW	Write Data Hold Time		1	-	-	ns
tPWLW	Write Low Time		12	-	-	ns
tDHR	Read Data Hold Time		1	-	-	ns
tACC	Access Time		32	-	-	ns
tPWLR	Read Low Time		36	-	-	ns
tR	Rise Time		-	-	0.5	ns
tF	Fall Time		-	-	0.5	ns
tCS	Chip select setup time		2	-	-	ns
tCSH	Chip select hold time to read signal		3	-	-	ns

* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)

Figure 1-3: Parallel 8080-series Interface Timing Diagram (Write Cycle)

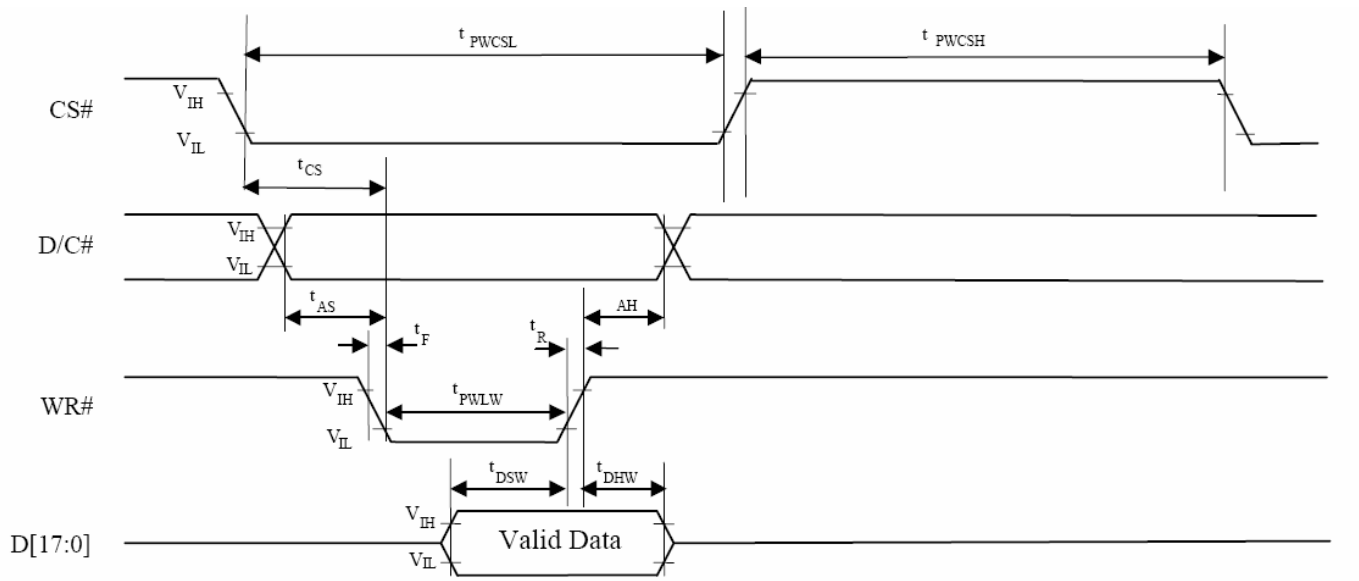
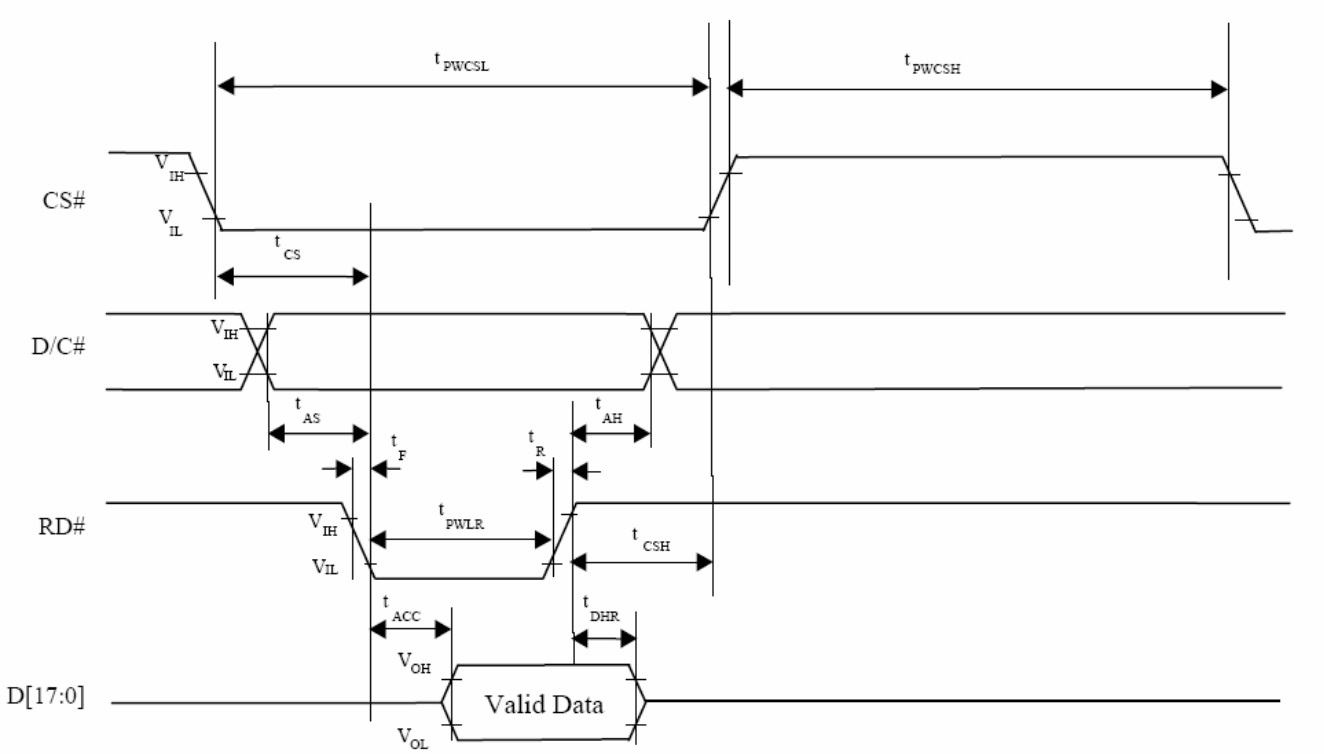


Figure 1-4: Parallel 8080-series Interface Timing Diagram (Read Cycle)



2. Data Transfer Order Setting

Pixel Data Format

Both 6800 and 8080 support 8-bit, 9-bit, 16-bit, 18-bit and 24-bit data bus. Depending on the width of the

data bus, the display data are packed into the data

Table 2-1: Pixel Data Format

Interface	Cycle	D[23]	D[22]	D[21]	D[20]	D[19]	D[18]	D[17]	D[16]	D[15]	D[14]	D[13]	D[12]	D[11]	D[10]	D[9]	D[8]	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]
24 bits	1st	R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
18 bits	1st							R5	R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	B0
16 bits (565 format)	1st									R5	R4	R3	R2	R1	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1
16 bits	1st									R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0
	2nd									B7	B6	B5	B4	B3	B2	B1	B0	R7	R6	R5	R4	R3	R2	R1	R0
	3rd									G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
12 bits	1st													R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4
	2nd													G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
9 bits	1st																R5	R4	R3	R2	R1	R0	G5	G4	G3
	2nd																G2	G1	G0	B5	B4	B3	B2	B1	B0
8 bits	1st																	R7	R6	R5	R4	R3	R2	R1	R0
	2nd																	G7	G6	G5	G4	G3	G2	G1	G0
	3rd																	B7	B6	B5	B4	B3	B2	B1	B0

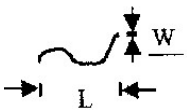
3. Register Depiction

Please consult the spec of SSD1963 Version 1.2

■ RELIABILITY TEST

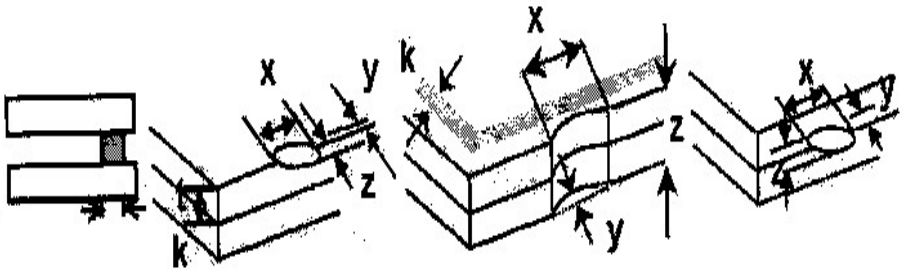
No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80±2℃/240 hours	
2	Low Temperature Storage	-30±2℃/240 hours	
3	High Temperature Operating	70±2℃/240 hours	
4	Low Temperature Operating	-20±2℃/240 hours	
5	Temperature Cycle	-20 ± 2 ℃ ~25~70 ± 2 ℃ × 10cycles (30min.) (5min.) (30min.)	
6	Damp Proof Test	60℃±5℃×90%RH/240 hours	

■ INSPECTION CRITERION

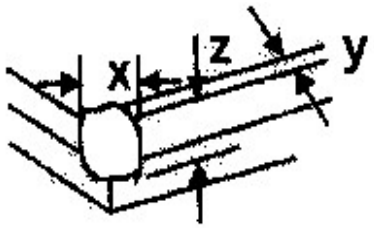
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x + y) / 2</td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table>
<tr><th>Length</th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

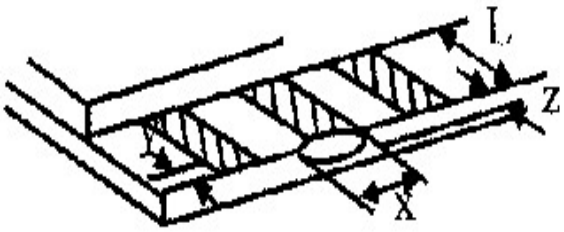
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>
Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

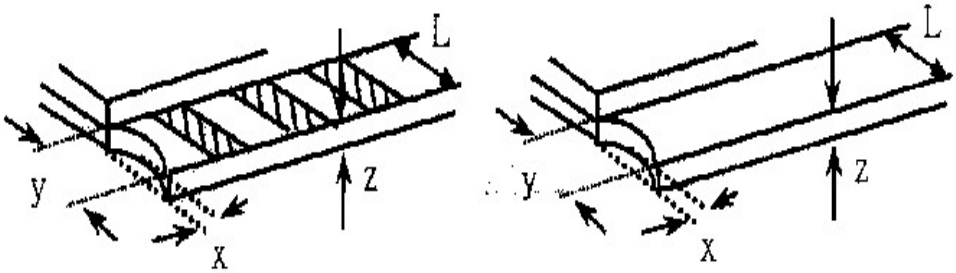
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:


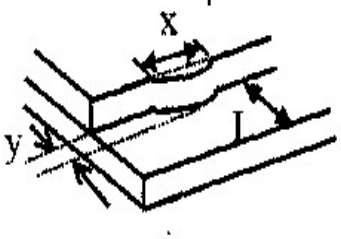
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:


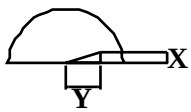
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is the total length of each chip.
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><th>y: width</th><th>x: length</th></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  **X * Y<=2mm^2**	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icide. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

■ PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

(1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.

(2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

(3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).

(4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.

(5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents

- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

(6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

(7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

(8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

(9) Do not attempt to disassemble or process the LCD module.

(10) NC terminal should be open. Do not connect anything.

(11) If the logic circuit power is off, do not apply the input signals.

(12) Electro-Static Discharge Control，Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated

（13）Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

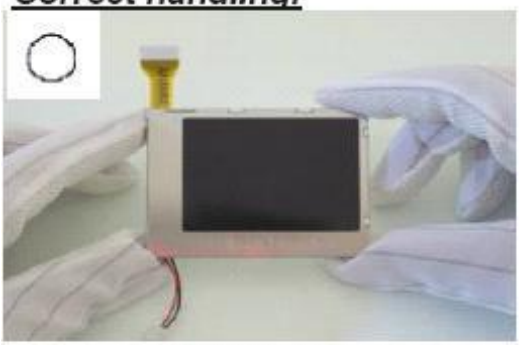
To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
-Terminal electrode sections.

Handling precaution for LCM

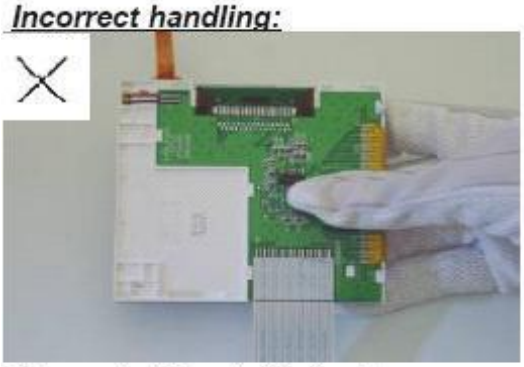
LCM is easy to be damaged.
Please note below and be careful for handling!

Correct handling:

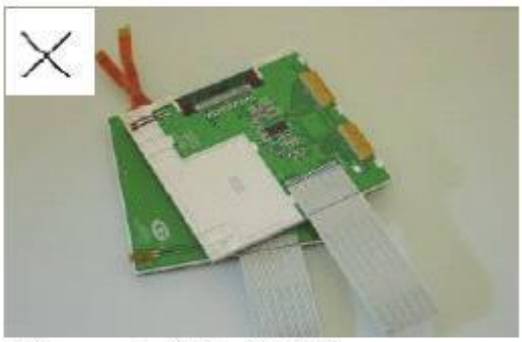


As above picture, please handle with anti-static gloves around LCM edges.

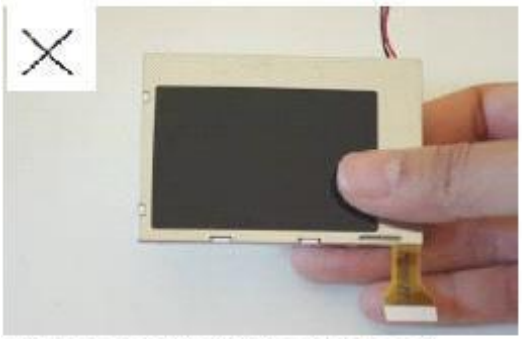
Incorrect handling:



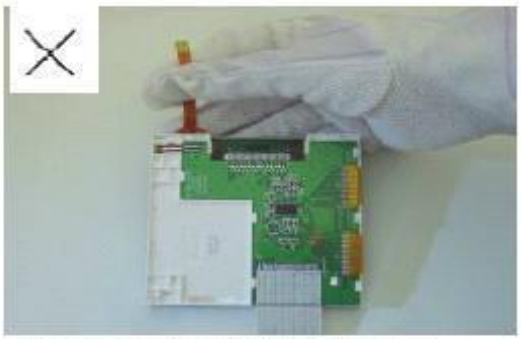
Please don't touch IC directly.



Please don't stack LCM.



Please don't hold the surface of panel.

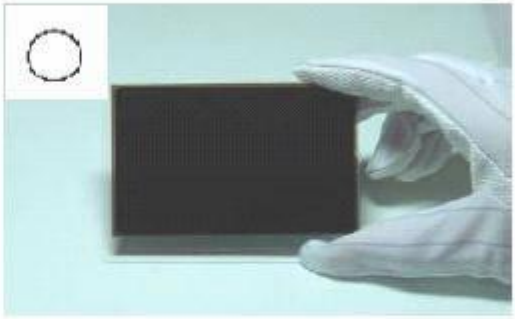


Please don't stretch interface of output, such as FPC cable.

Handling precaution for LCD

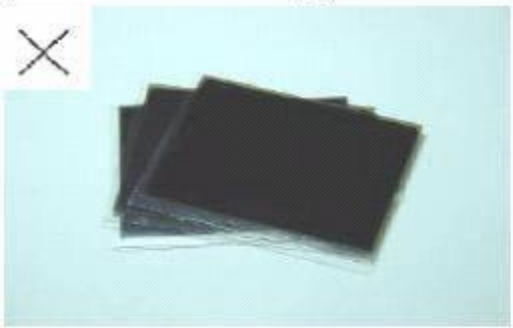
LCD is easy to be damaged.
Please note below and be careful for handling!

Correct handling:

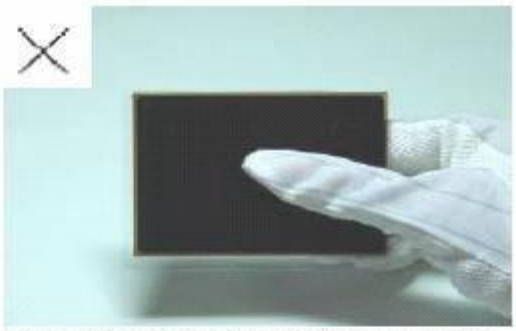


As above photo, please handle with anti-static gloves around LCD edges.

Incorrect handling:

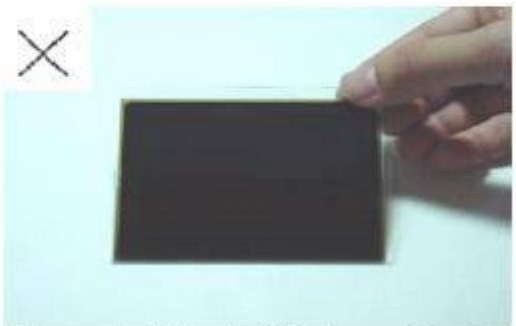


Please don't stack the LCDS.



Please don't hold the surface of LCD.

Please don't operate with sharp stick such as pens.



Please don't touch ITO glass without anti-static gloves.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the anti-static electricity container in which they were shipped.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

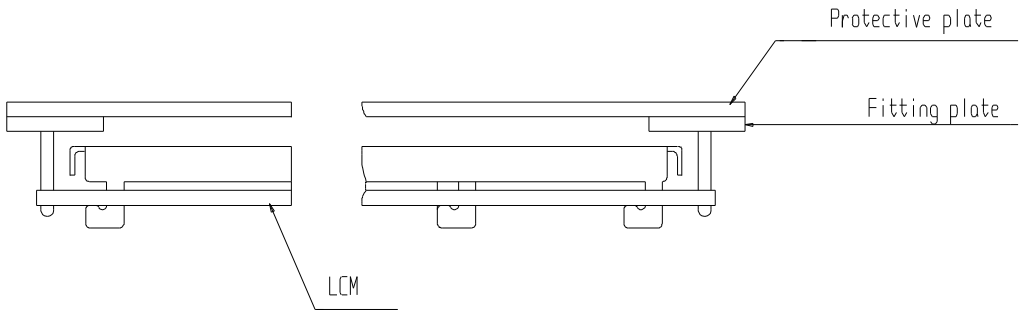
- Exposed area of the printed circuit board.
-Terminal electrode sections.

USING LCD MODULES

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

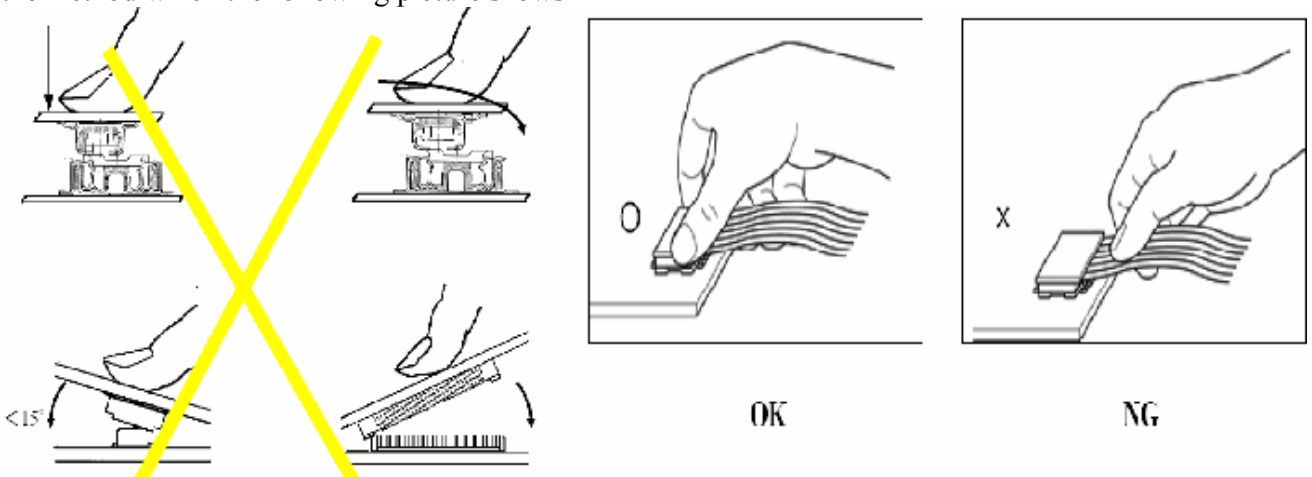
(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ±0.1mm.

Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position,don't assemble or assemble like the method which the following picture shows



Precaution for soldering to the LCM

	Hand soldering	Machine drag soldering	Machine press soldering
No ROHS product	290°C ~350°C. Time : 3-5S.	330°C ~350°C. Speed : 4-8 mm/s.	300°C ~330°C. Time : 3-6S. Press: 0.8~1.2Mpa
ROHS product	340°C ~370°C. Time : 3-5S.	350°C ~370°C. Time : 4-8 mm/s.	330°C ~360°C. Time : 3-6S. Press: 0.8~1.2Mpa

(1) If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

(2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

(3) When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

(1) Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

(2) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

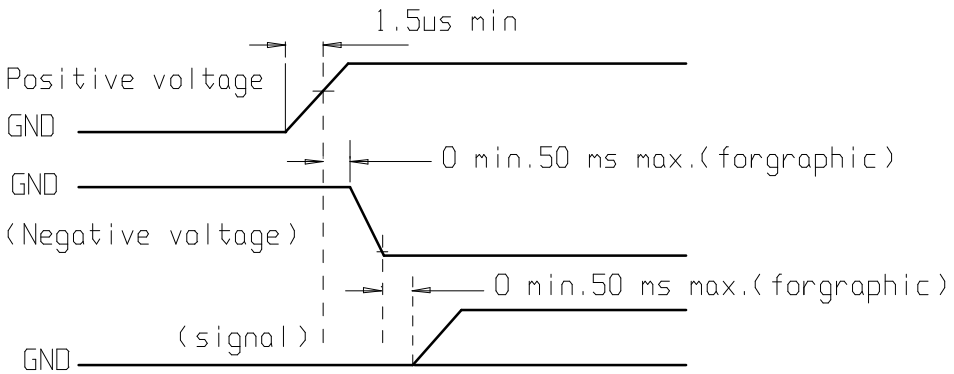
(3) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, Which will come back in the specified operating temperature.

(4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

(5) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature,50%RH or less is required.

(6) Input each signal after the positive/negative voltage becomes stable.

(7) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.



Safety

(1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

(2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

Limited Warranty

Unless agreed betweenMulti-Inno and customer,Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replacement on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
- PCB eyelet is damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

■ PRIOR CONSULT MATTER

1.①For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without notice on our customer.

②For OEM products, if any change needed which may affect the product property, we will consult with our customer in advance.

2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.